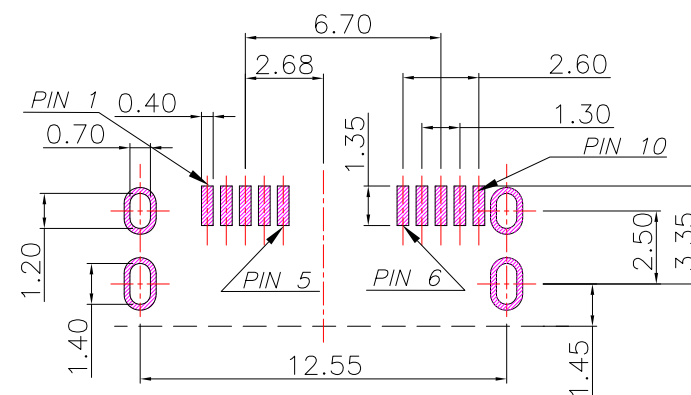
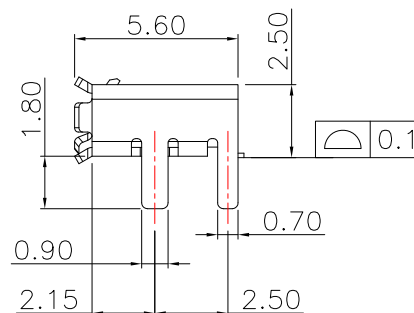
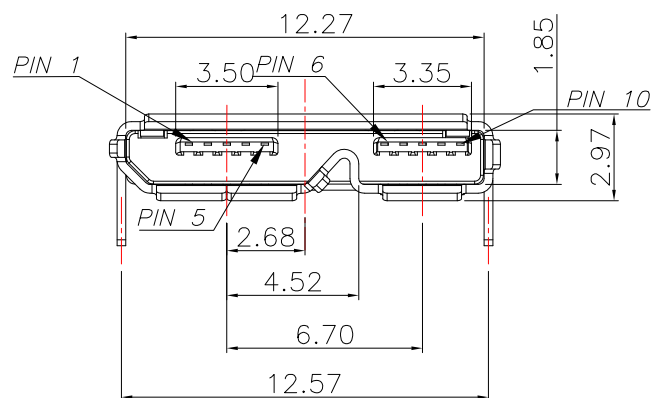
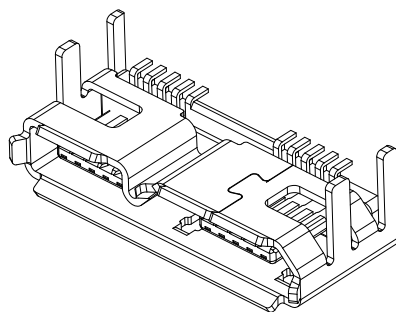
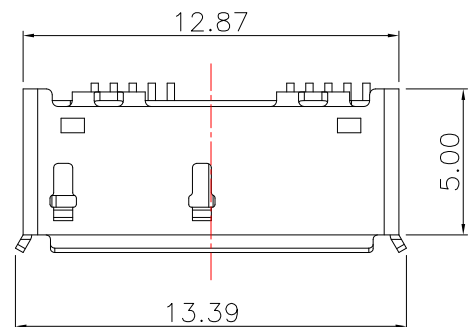




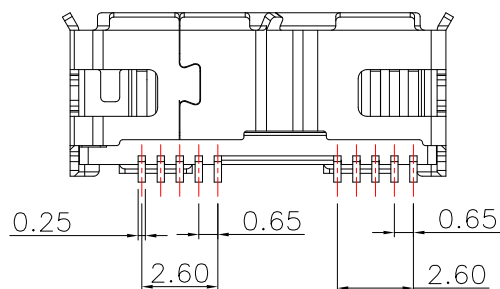
# MRUSB-10B-D4-30x-S277

鍍層厚度:

Blank	: 1u"
2	: 15u"
3	: 30u"



P.C.B LAYOUT MOUNTING PATTERN



**NOTE:**

**1.MATERIAL:**

- 1.1 INSULATOR: LCP, UL 94V-0
- 1.2 CONTACT: BRASS
- 1.3 SHELL: SUS 304

**2.Finish:**

- 2.1 CONTACT: PLATED GOLD IN MATING AREA ;  
TIN PLATED ON SOLDER BALLS ;  
NICKEL UNDER PLATED OVERALL
- 2.2 SHELL: NICKEL UNDER PLATED SURFACE LAYER

**CONTACT** 建倚科技股份有限公司  
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED :  
Up to 5 ±0.2  
Above 5 ~ 15 ±0.3  
Above 15 ~ 30 ±0.4  
Above 30 ~ 50 ±0.5  
Angle ±0.3

3RD. ANGEL'S



UNITS MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	03/13/15		MODLE	MICRO USB 3.0 B 型 母座 SMT 外殼 4腳 DIP
CHECKED BY:	DATE	FINISH	DWG NO.	MRUSB-10B-D4-30x-S277
Jacky Chen	03/13/15		PART NO.	MRUSB-10B-D4-30x-S277
APPROVED BY:	DATE	SCALE	SHEET NO.	1 of 1
Tony Kao	03/13/15	1 : 1		

1	新增pin定義	Jack	031315
ITEM NO.	DESCRIPTION	DRAWN	DATE